

Electronic Patent Application Fee Transmittal

Application Number:	10724981			
Filing Date:	30-Nov-2003			
Title of Invention:	DIE-FIRST MULTI-CHIP MODULES AND METHODS OF MANUFACTURE			
First Named Inventor/Applicant Name:	Wendy Lee Wilkins			
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Attorney Docket Number:	13312/111			
Filed as Small Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	2501	1	720	720
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1020